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(12) **United States Design Patent**
Feng

(10) **Patent No.:** **US D745,473 S**

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(54) **LIGHT EMITTING DIODE CHIP**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**

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D25/155, 160, 163; D26/1

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H01L 33/10; H01L 33/20; H01L 33/38;
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H01L 33/486; H01L 24/06; H01J 3/021;
H01S 5/34; F21K 9/00; F21K 9/30; F21K
9/54; B82Y 20/00; B82Y 40/00

See application file for complete search history.

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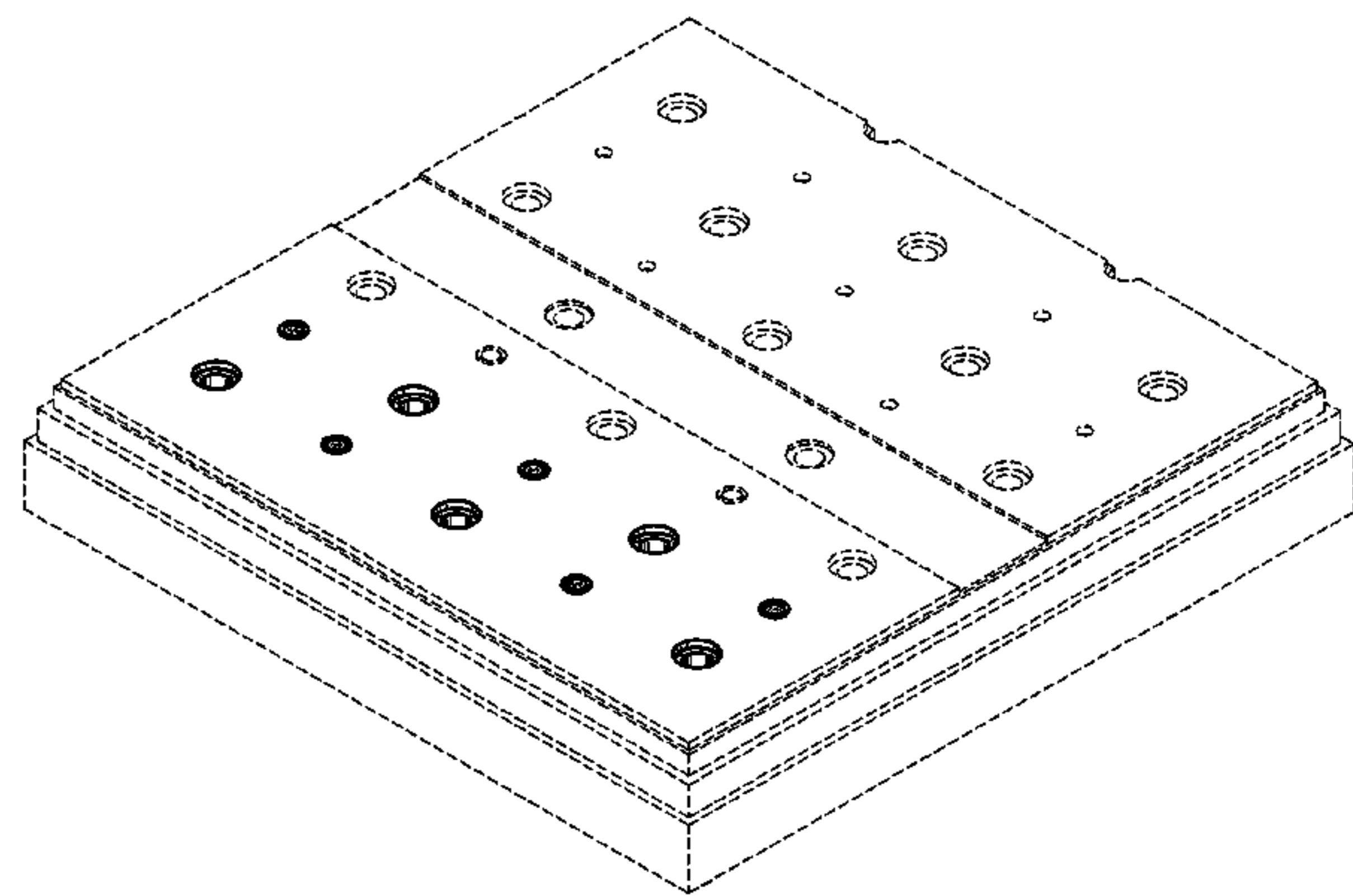
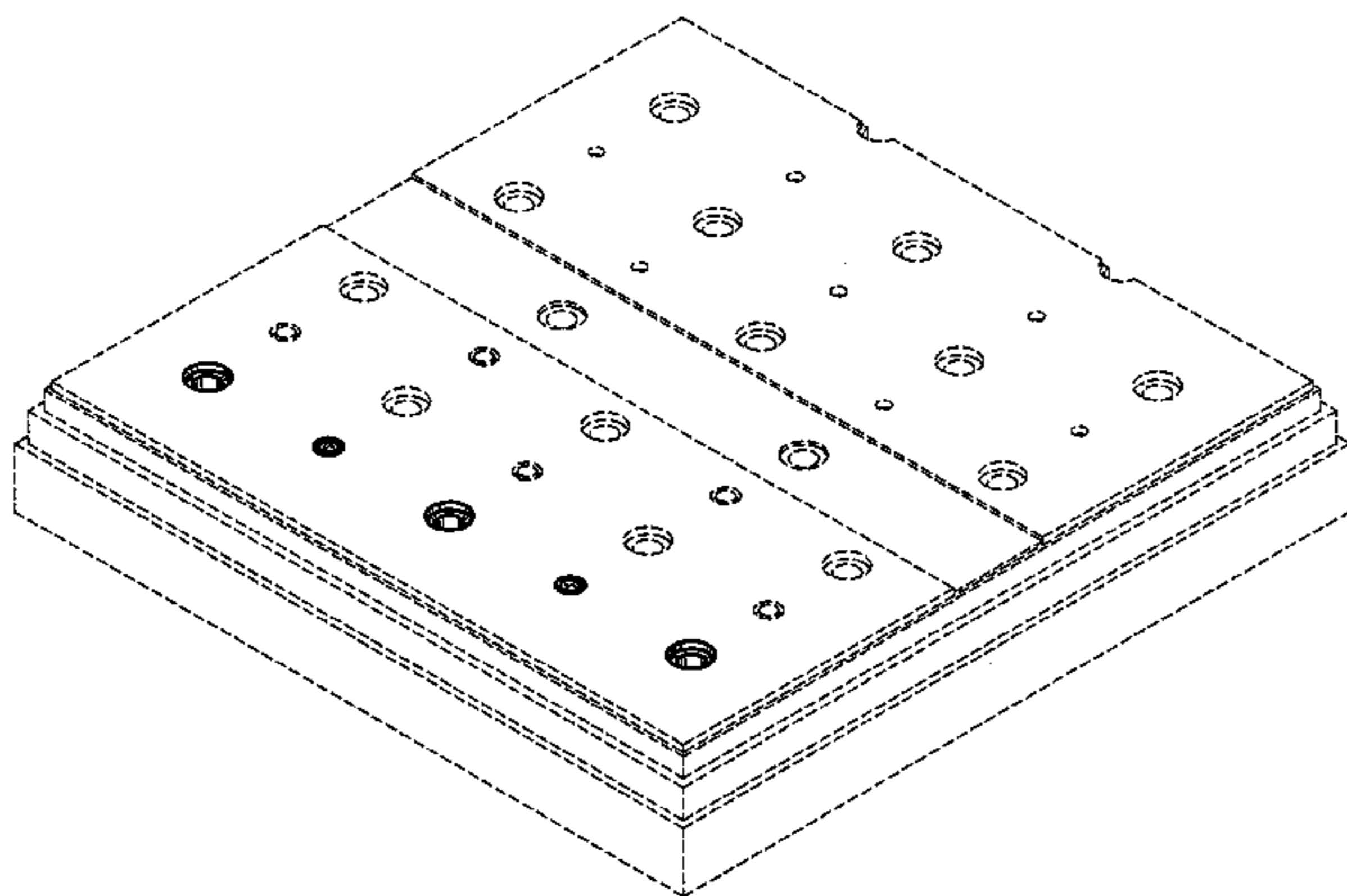
(57) **CLAIM**

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing a first embodiment of my new design; FIG. 2 is a front view of the first embodiment; FIG. 3 is a rear view of the first embodiment; FIG. 4 is a left side view of the first embodiment; FIG. 5 is a right side view of the first embodiment; FIG. 6 is a top view of the first embodiment; FIG. 7 is a bottom view of the first embodiment; FIG. 8 is a perspective view of the light emitting diode chip showing an alternate environment; FIG. 9 is a front view thereof; FIG. 10 is a rear view thereof; FIG. 11 is a left side view thereof; FIG. 12 is a right side view thereof; FIG. 13 is a top view thereof; FIG. 14 is a bottom view thereof; FIG. 15 is a perspective view of a light emitting diode chip showing a second embodiment of my new design; FIG. 16 is a front view of the second embodiment; FIG. 17 is a rear view of the second embodiment; FIG. 18 is a left side view of the second embodiment; FIG. 19 is a right side view of the second embodiment; FIG. 20 is a top view of the second embodiment; and, FIG. 21 is a bottom view of the second embodiment. The broken line portions of the light emitting diode chip in FIGS. 1-21 represent unclaimed portions of the design and form no part thereof.

1 Claim, 15 Drawing Sheets



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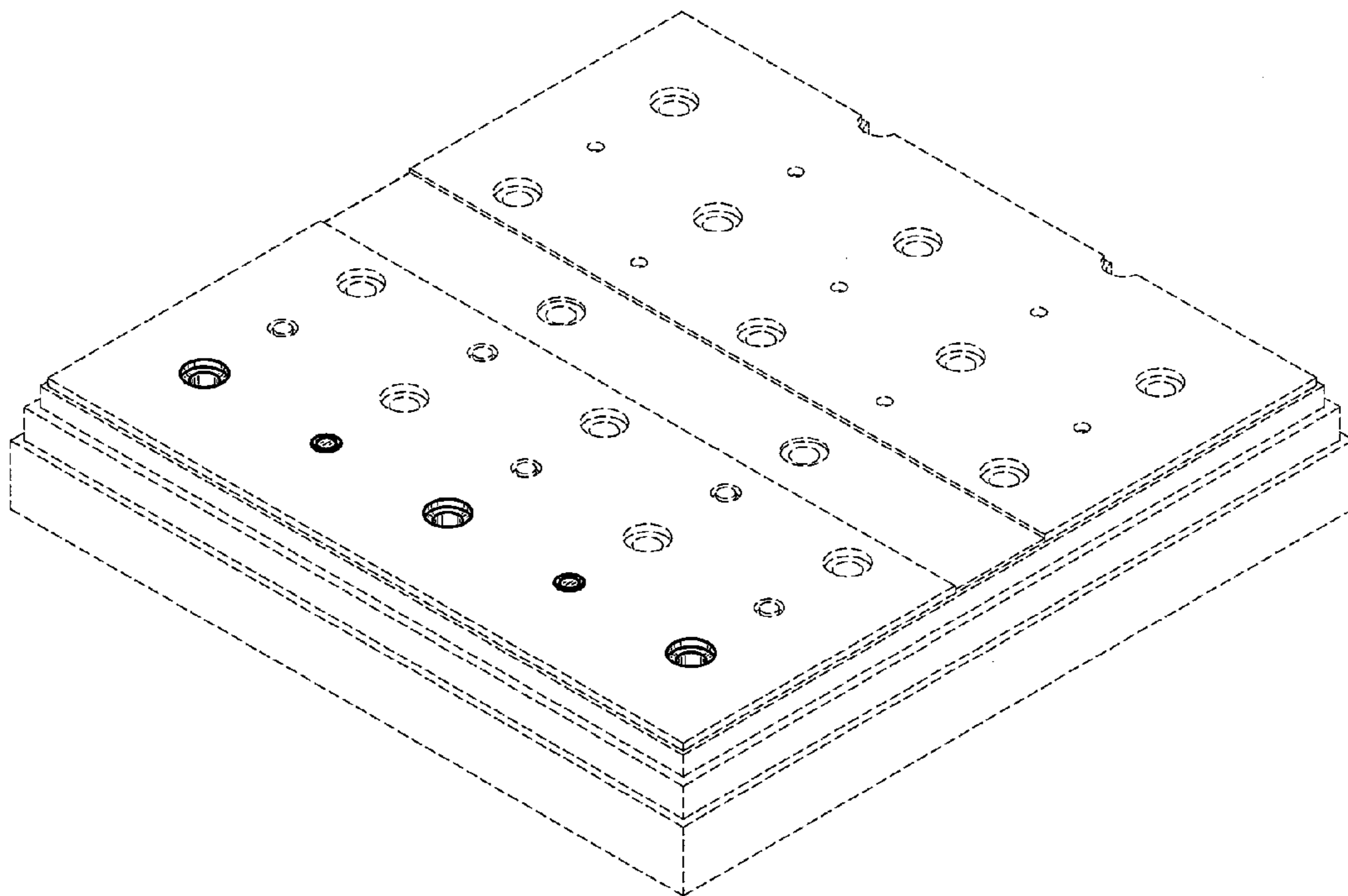


FIG. 1

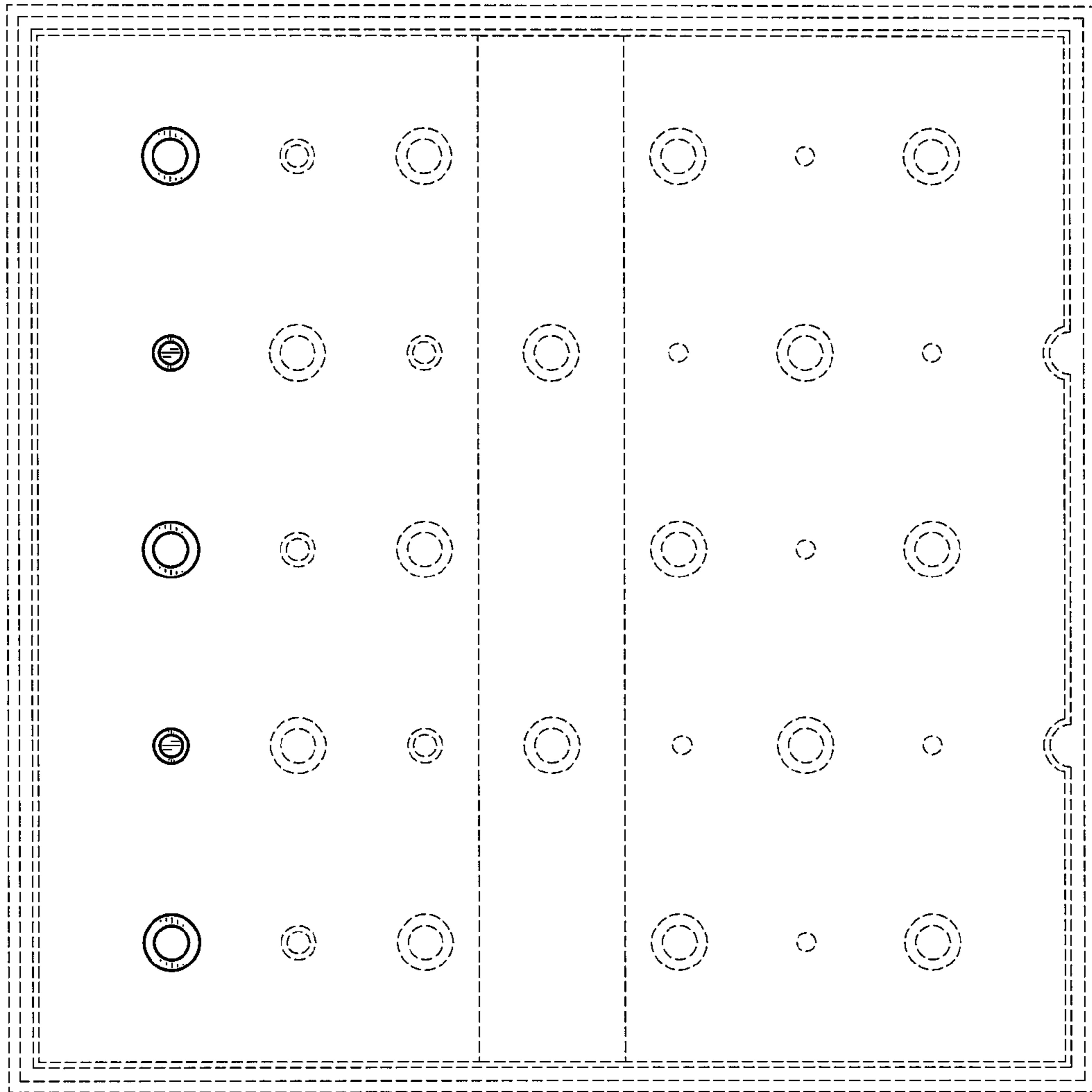


FIG. 2

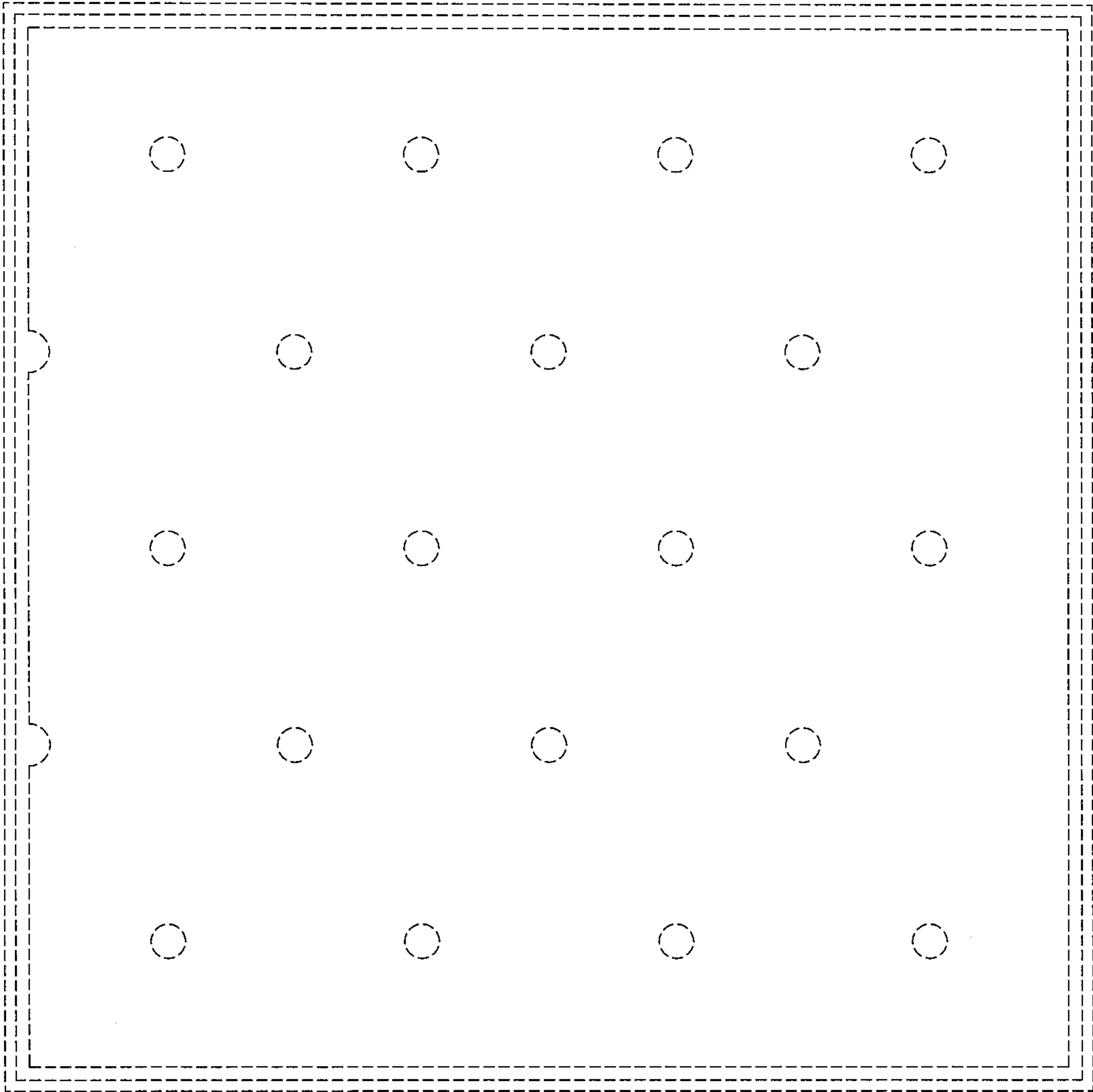


FIG. 3

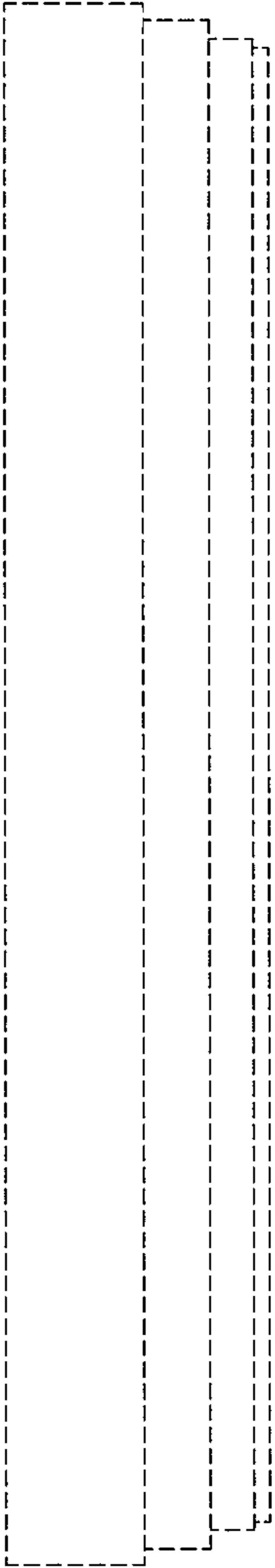


FIG. 4

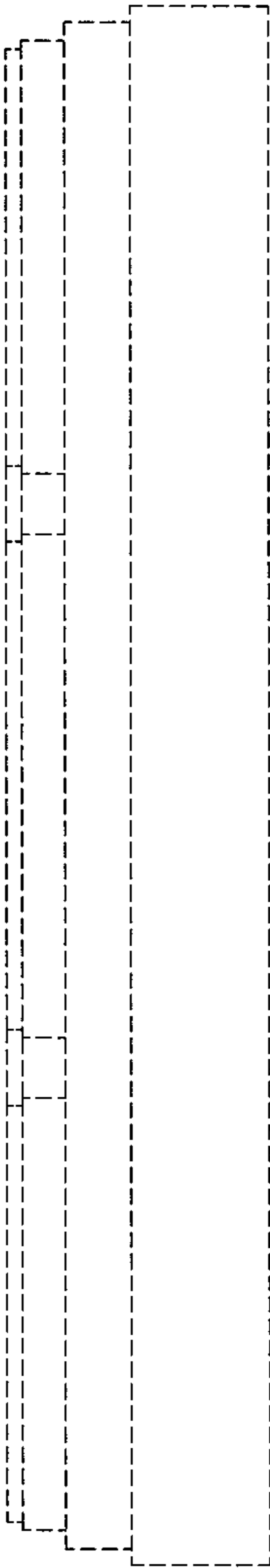


FIG. 5

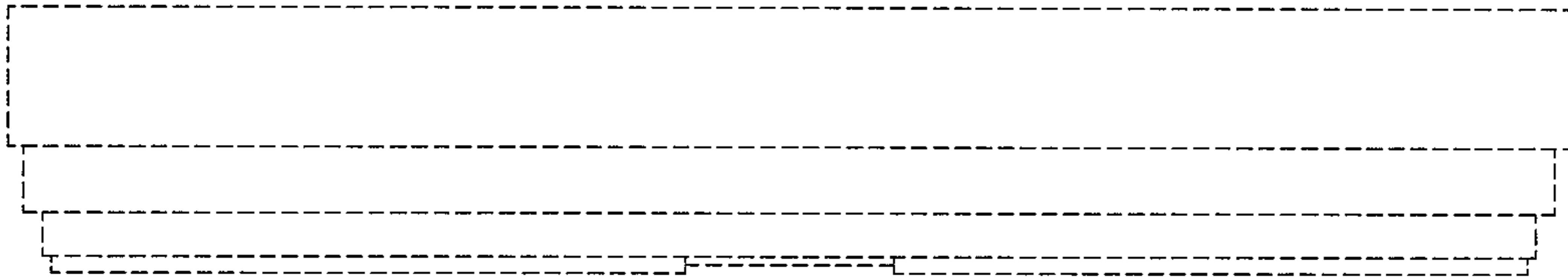


FIG. 6

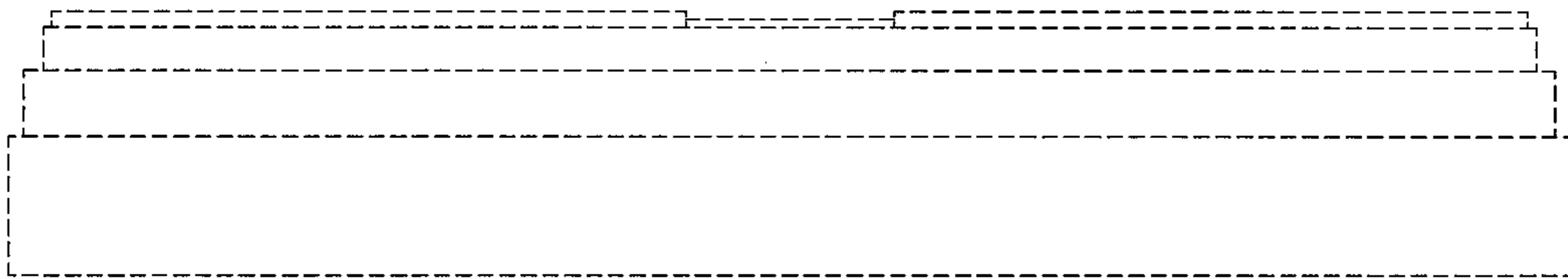


FIG. 7

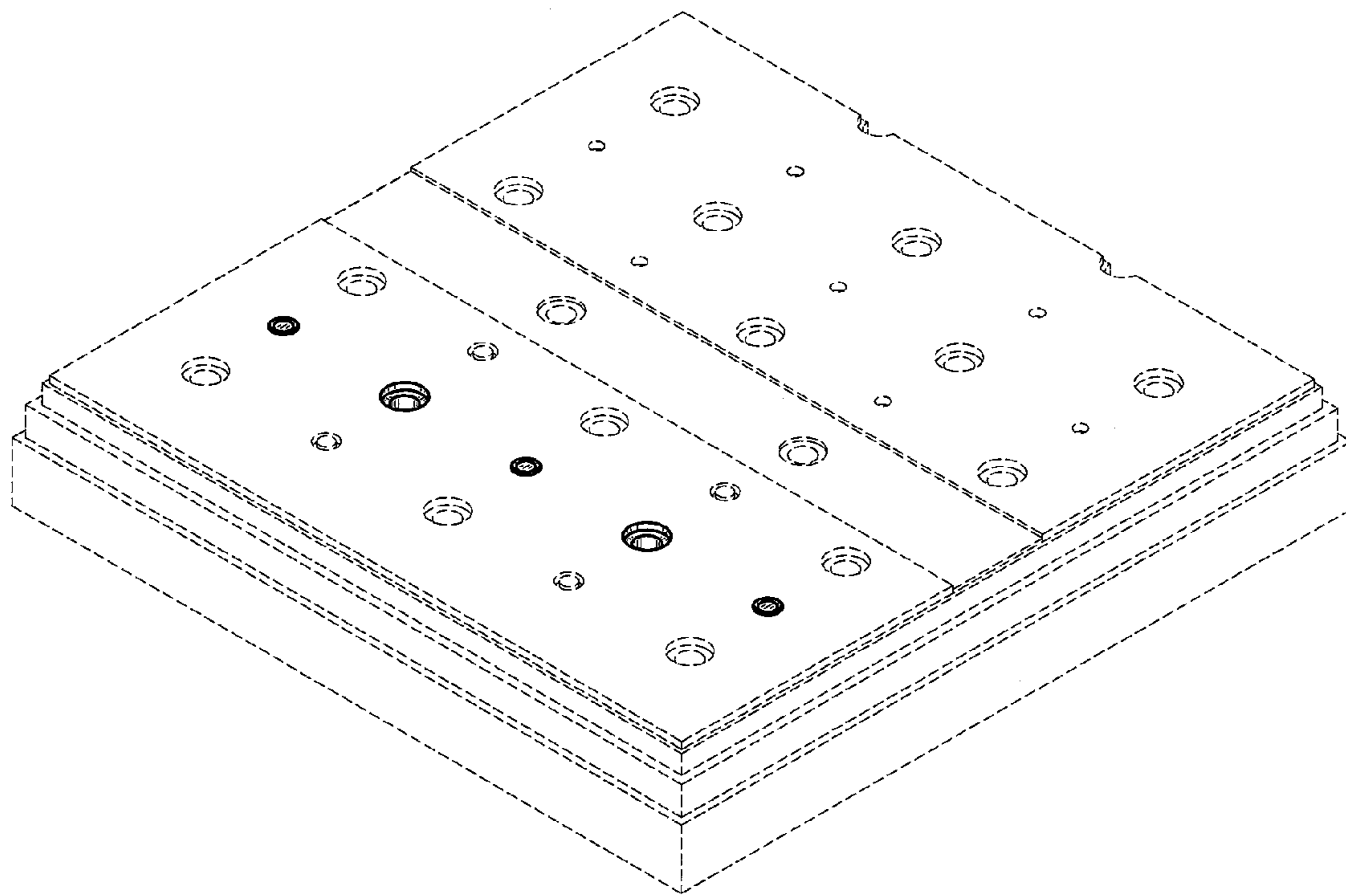


FIG. 8

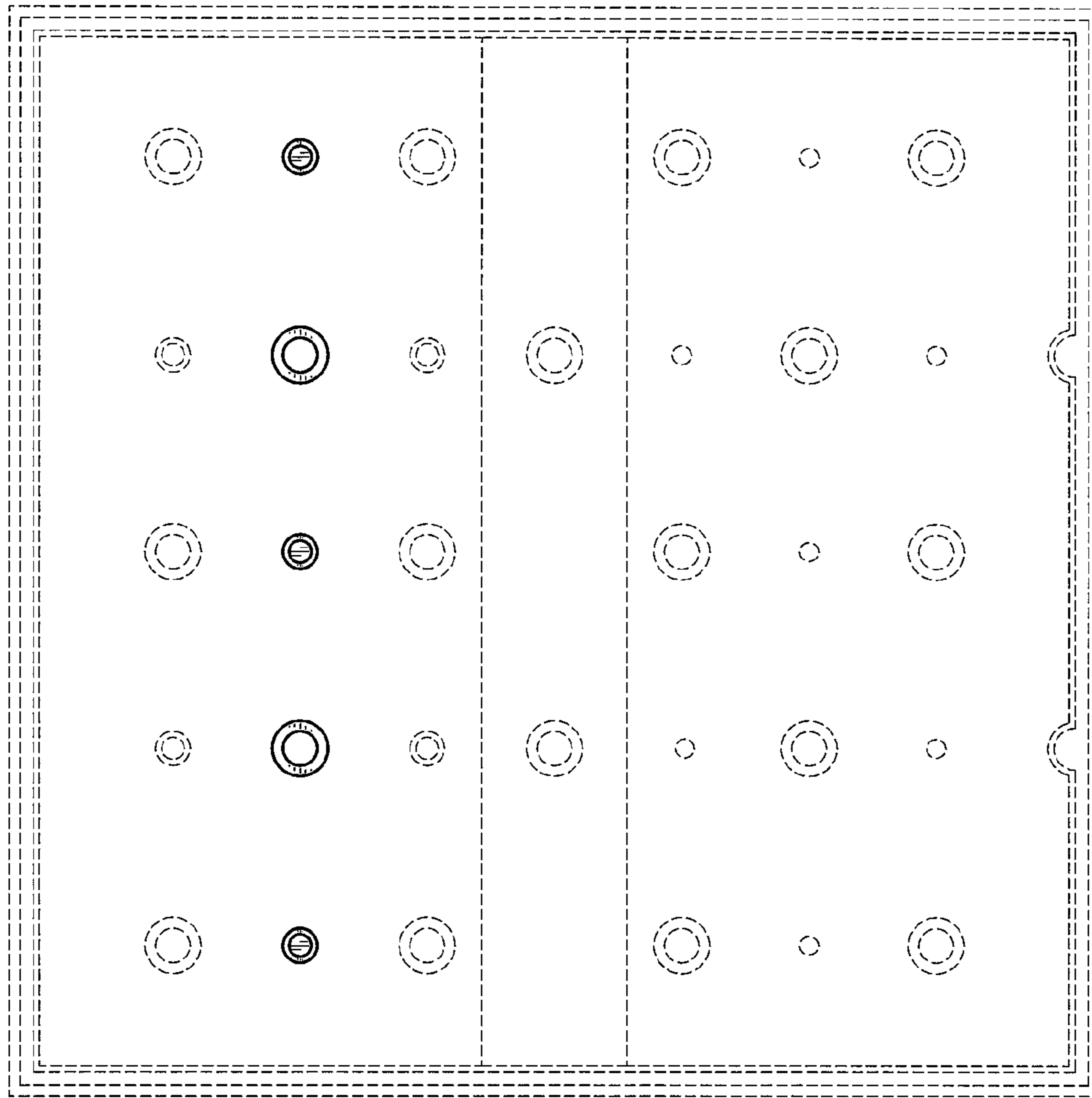


FIG. 9

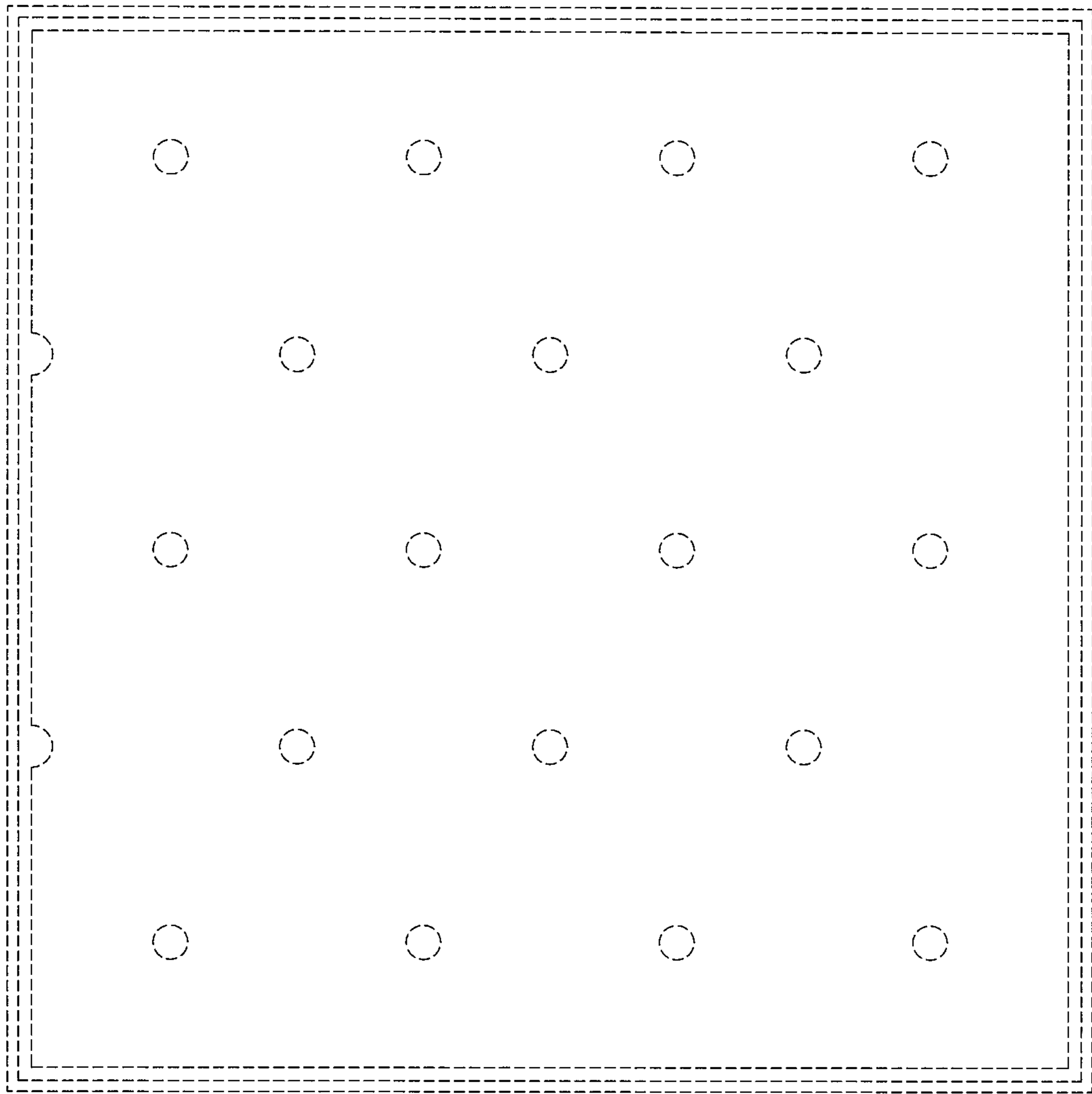


FIG. 10

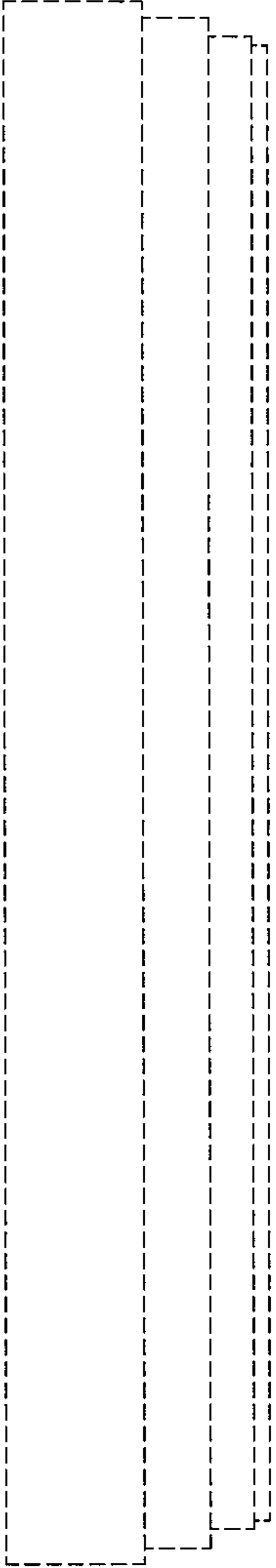


FIG. 11

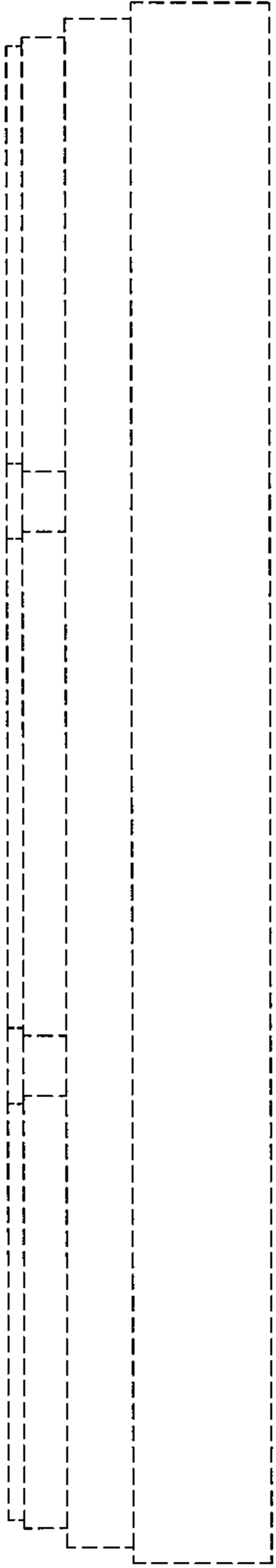


FIG. 12

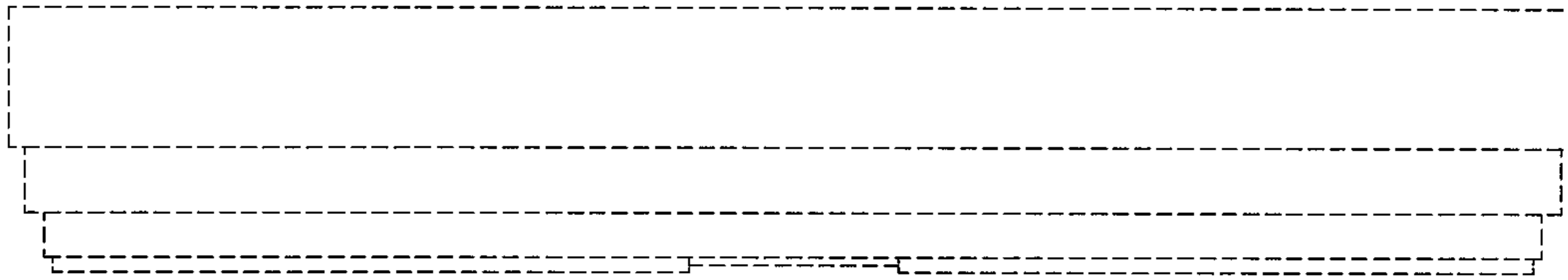


FIG. 13

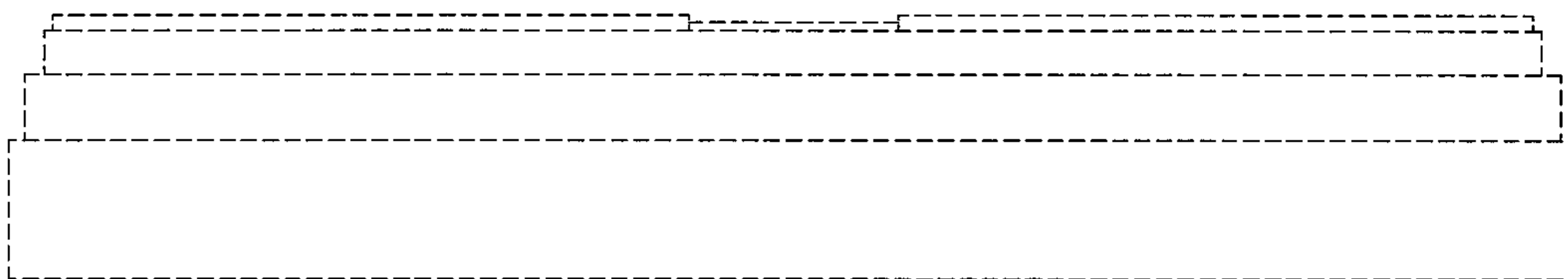


FIG. 14

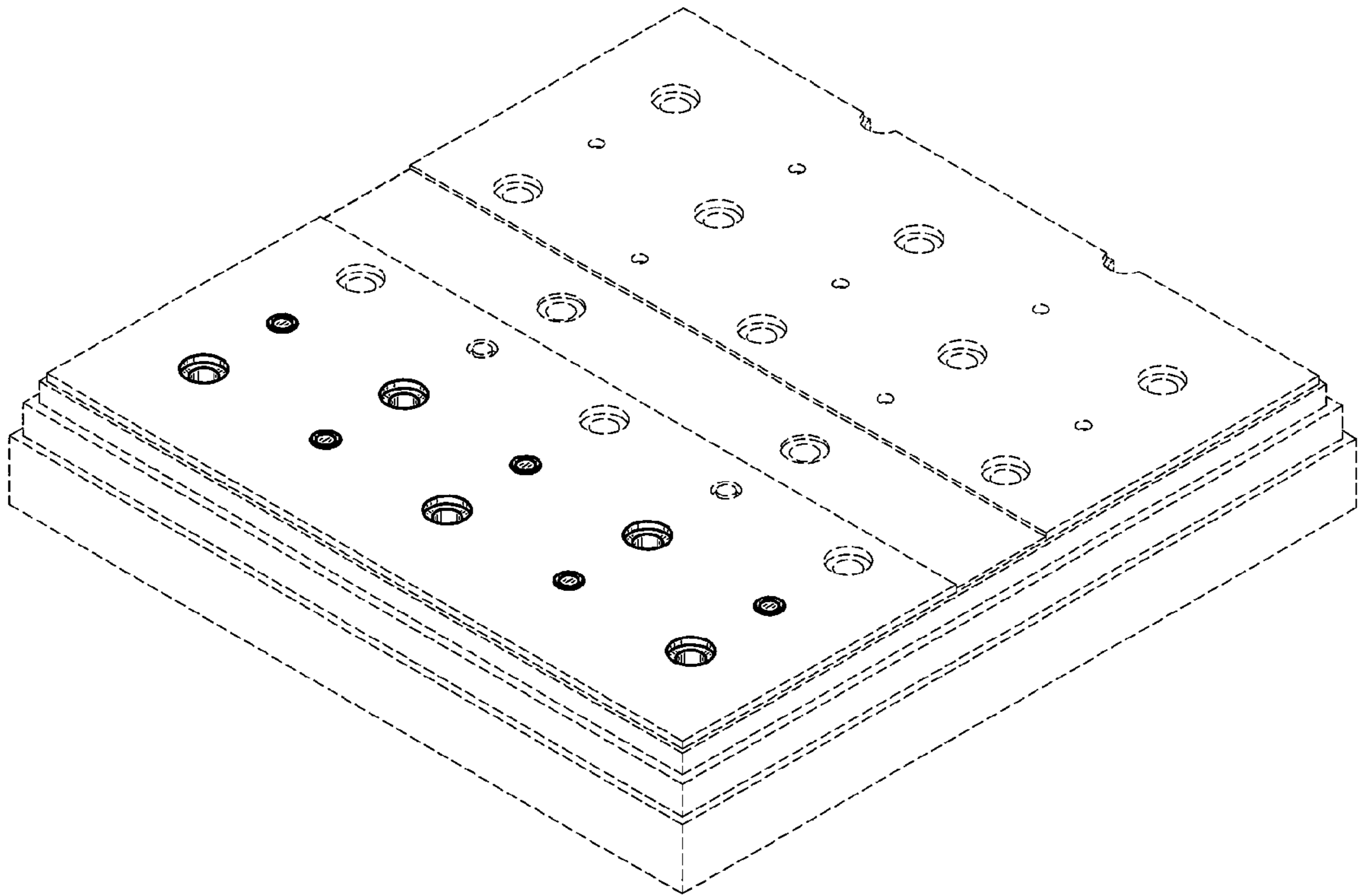


FIG. 15

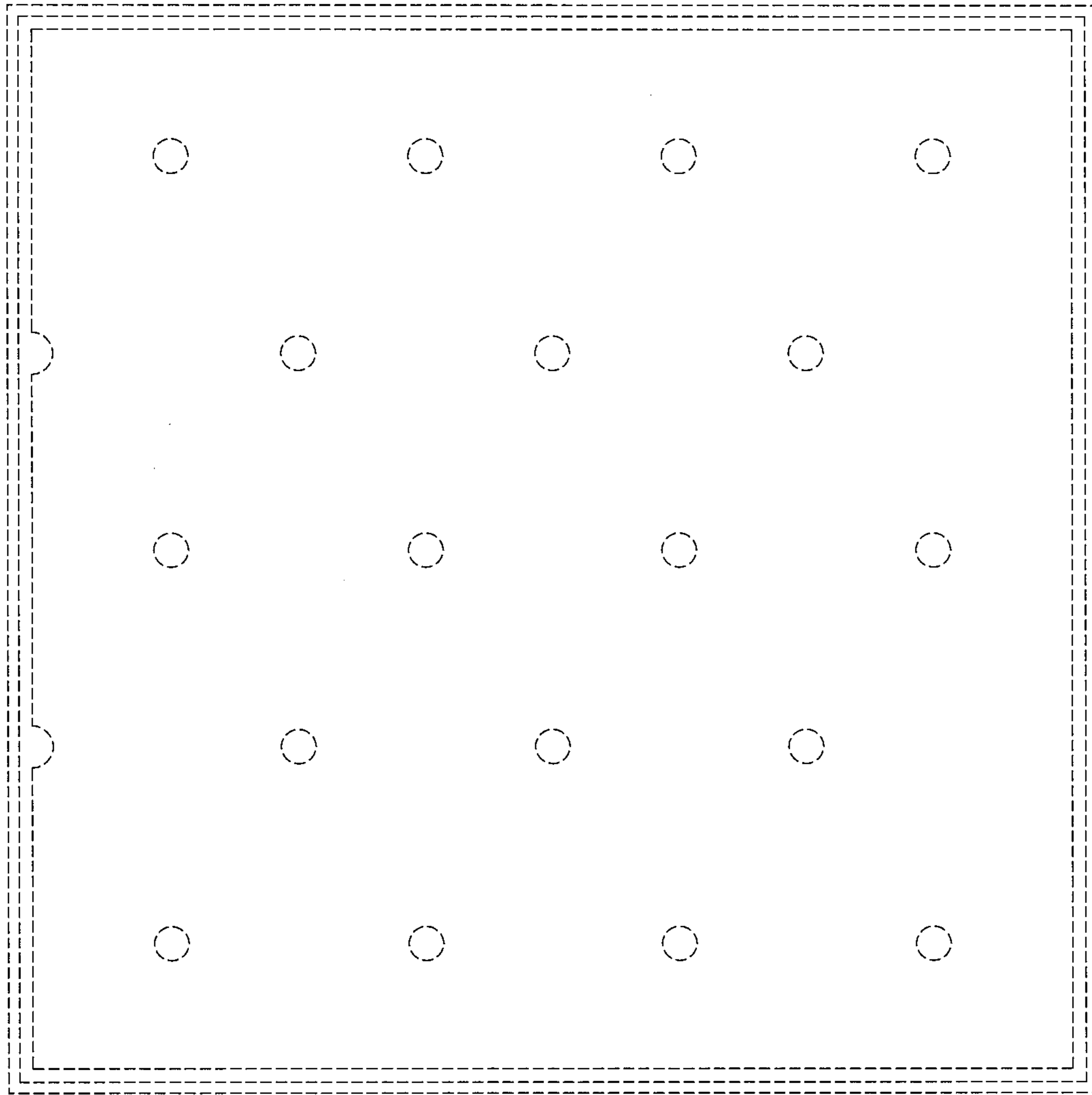


FIG. 17

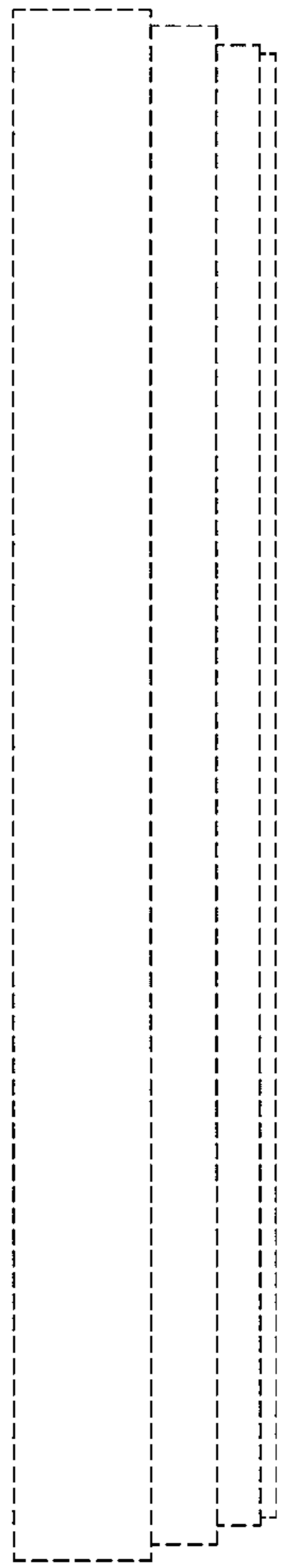


FIG. 18

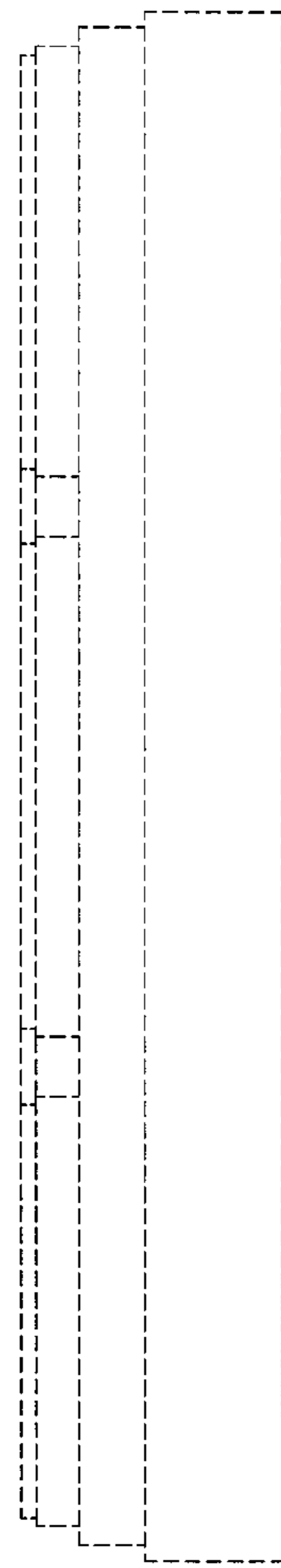


FIG. 19

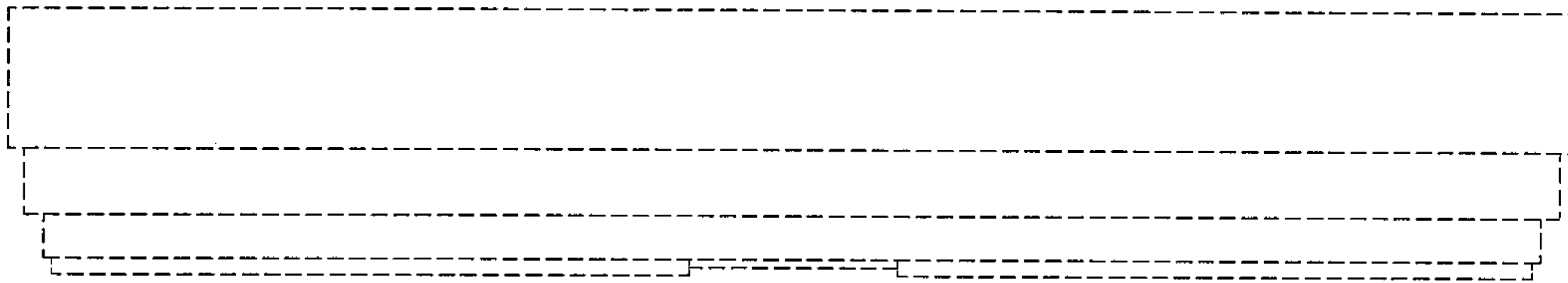


FIG. 20

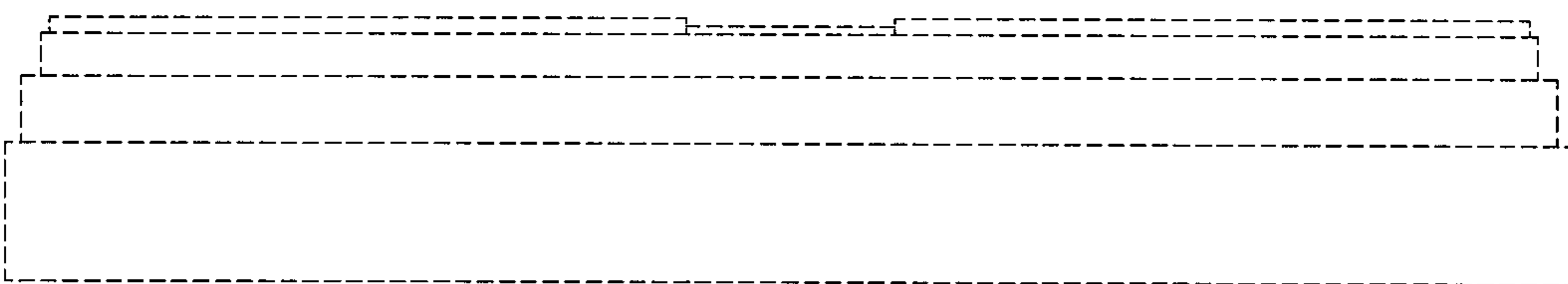


FIG. 21